



Discription

The HSPHV12-01ETG-C protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD. It gives designer the flexibility to protect one unidirectional line in applications where arrays are not practical.



DFN1006-2L

Features

- ★ Transient protection for high-speed data lines
IEC 61000-4-2(ESD) ±8kV (Contact)
±15kV (Air)
IEC 61000-4-4(EFT) 40A (5/50 ns)
- ★ Peak power dissipation: 150W (8/20us)
- ★ Working voltages : 12V
- ★ Ultra-small package (1.0mmx0.6mmx0.5mm)
- ★ Protects one data, control line
- ★ Low capacitance: 45pF (Typical)
- ★ Low clamping voltage
- ★ Low leakage current



Circuit Diagram

Ordering information

Product ID	Pack	Qty(PCS)
HSPHV12-01ETG-C	DFN1006-2L	10000

Absolute Ratings(Tamb = 25°C)

Symbol	Parameter	Value	Units
P _{PP}	Peak Pulse Power (t _p = 8/20 μ s)	150	W
T _L	Maximum lead temperature for soldering during 10s	260	°C
T _{stg}	Storage Temperature Range	-55 to +150	°C
T _{op}	Operating Temperature Range	-55 to +150	°C
T _j	Maximum junction temperature	150	°C
	IEC61000-4-2 (ESD)	air discharge ± 15 contact discharge ± 8	KV
	IEC61000-4-4 (EFT)	40	A



Electrical Characteristics Ratings at 25°C

Symbol	Parameter	Test Condition	Min	Typ	Max	Units
V_{RWM}	Reverse Working Voltage				12	V
V_{BR}	Reverse Breakdown Voltage	$I_T = 1\text{mA}$	13.3			V
I_R	Reverse Leakage Current	$V_{RWM} = 12\text{V}$			1000	nA
V_C	Clamping Voltage	$I_{RWM} = 1\text{A}, t_p = 8/20\mu\text{s}$			20	V
		$I_{RWM} = 4\text{A}, t_p = 8/20\mu\text{s}$			26	V
C_J	Junction Capacitance	$V_R = 0\text{V}, f = 1\text{MHz}$		28	35	pF

Typical Characteristics

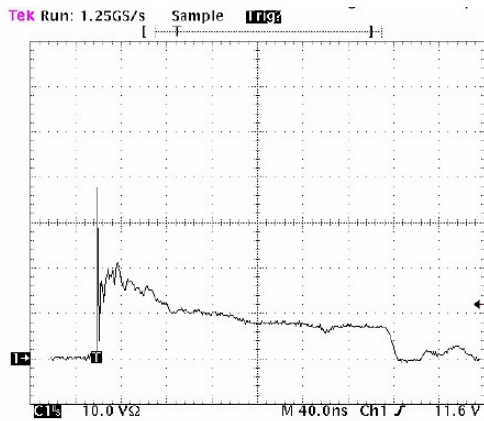


Figure 1. ESD Clamping Voltage Screenshot
Positive 8 kV contact per IEC 61000-4-2

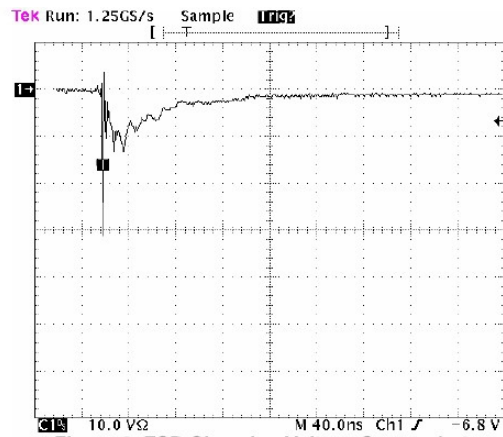


Figure 2. ESD Clamping Voltage Screenshot
Negative 8 kV contact per IEC 61000-4-2



Outline And Dimensions



TOP VIEW

BOTTOM VIEW

DFN1006-2L			
Dim	Min	Typ	Max
D	0.95	1.00	1.05
E	0.55	0.60	0.65
e	-	0.64	-
L	0.44	0.49	0.54
b	0.20	0.25	0.30
A	0.43	0.48	0.53
A1	0	-	0.05
A3	0.127REF.		
All Dimensions in mm			



SIDE VIEW

Soldering Footprint



Dimensions	(mm)
c	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70



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